$MA221,\ MA222,\ MA223$

Silicon epitaxial planer type

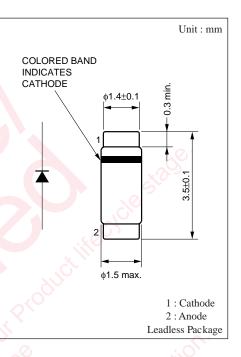
For high speed switching circuits

Features

- Extra-small cylindrical package, most favorable for high-density mounting
- Overall dimensions similar to those of resistor and capacitor (1/8W type), enabling sharing of the mounted equipment
- \bullet High switching speed and small capacity between pins, \underline{C}_t

Parameter	Symbol	Rating	Unit		
	MA221		35	V	
Reverse voltage (DC)	MA222	V _R	50		
	MA223		75		
Repetitive peak reverse voltage	MA221		35	V	
	MA222	V _{RRM}	50		
	MA223		75		
Average forward current		I _{F (AV)}	100	mA .	
Peak forward current	I _{FRM}	225	mA		
Non-repetitive peak forward surge current		I _{FSM} *	500	mA	
Junction temperature	Tj	200	°C		
Storage temperature	T _{stg}	- 55 to +150	°C		





* t=1s

Electrical Characteristics (Ta= 25°C)

Parameter		Symbol	Condition	min	typ	max	Unit	
MA22	MA 221	- Chr	V _R =15V	-0		25	nA	
	MAZZI	^O	V _R = 30V	S		0.1	μΑ	
	MA222		V _R =15V			25	nA	
	MAZZZ	I _R	V _R = 50V			5	μΑ	
	14000		$V_{R}=20V$			25	nA	
	MA225		V _R =75V			5	μΑ	
	MA221		V _R = 35V, Ta=150°C			100		
	MA222	I _R	$V_R=50V$, Ta=150°C			100	μΑ	
	MA223		V_{R} = 75V, Ta=150°C			100		
Forward voltage (DC))	VF	I _F =100mA		0.95	1.2	V	
Reverse voltage (DC)	MA221	VR	$I_R = 5\mu A$	35			V	
Terminal capacitance		Ct	$V_R = 0V$, f=1MHz			2	pF	
Reverse recovery time	MA221	t _{rr} *	I _F =10mA, V _R =1V			10	ns	
	MA222/223		$I_{rr}=0.1\cdot I_R, R_L=100\Omega$		2.2	4		

Rated input/output frequency : 100MHz (MA221), 250MHz (MA222, MA223)

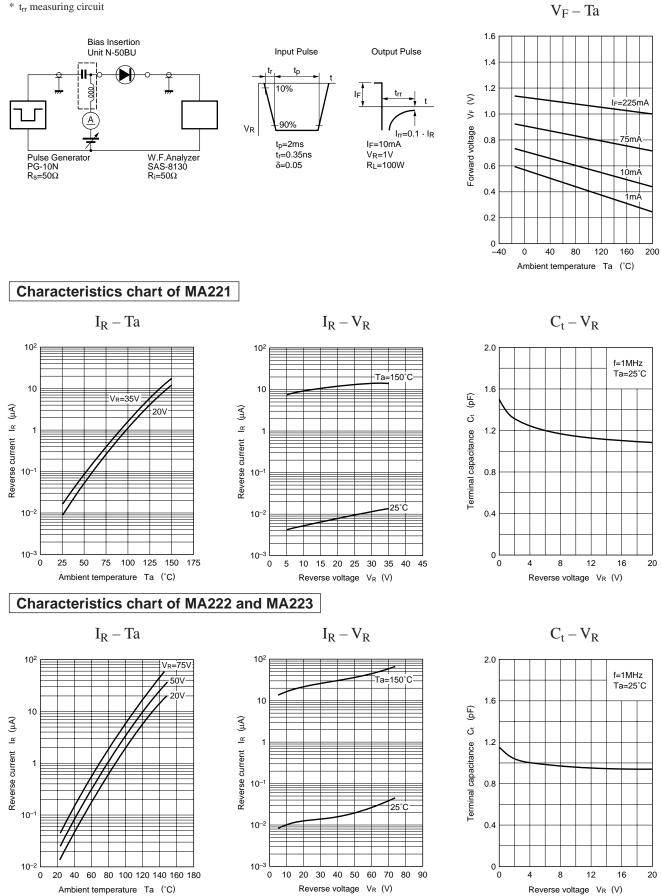
Cathode Indication

Type No.	MA221	MA222	MA223
Color	White	Green	Purple

Panasonic

Common characteristics chart







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